

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7688197

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the CONVEYING PARTY DATA/ASSIGNOR previously recorded on Reel 049279 Frame 0127. Assignor(s) hereby confirms the ASSIGNMENT.
CONVEYING PARTY DATA	
Name	Execution Date
BONG JIN SEO	05/14/2019
BON KEE KIM	05/14/2019
MYUNG JUN JIN	05/14/2019
TAE HUN KIM	05/14/2019
RECEIVING PARTY DATA	
Name:	HIDEEP INC.
Street Address:	(DASAN TOWER, SAMPYEONG-DONG) 3F, 49
Internal Address:	DAEWANGPANGYO-RO 644BEON-GIL, BUNDANG-GU,
City:	SEONGNAM-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
Postal Code:	13493
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16464064
CORRESPONDENCE DATA	
Fax Number:	(215)735-9305
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2157359302
Email:	uspto@thebellesgroup.com
Correspondent Name:	THE BELLES GROUP P.C.
Address Line 1:	1800 JOHN F. KENNEDY BOULEVARD SUITE 1010
Address Line 4:	PHILADELPHIA, PENNSYLVANIA 19103
ATTORNEY DOCKET NUMBER:	KNP-214-US
NAME OF SUBMITTER:	ELA RIMKUS
SIGNATURE:	/Ela Rimkus/
DATE SIGNED:	12/12/2022
Total Attachments: 6	

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PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1

Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
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Correspondent Name:	THE BELLES GROUP, P.C.
Address Line 1:	337 S. 18TH STREET
Address Line 4:	PHILADELPHIA, PENNSYLVANIA 19103

ATTORNEY DOCKET NUMBER:	KNP-214-US
NAME OF SUBMITTER:	TARA FROMM
Signature:	/Tara Fromm/
Date:	05/24/2019

Total Attachments: 2 source=KNP-214-US_Executed_Assignment#page1.tif source=KNP-214-US_Executed_Assignment#page2.tif	
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RECEIPT INFORMATION	
EPAS ID:	PAT5540262
Receipt Date:	05/24/2019

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ASSIGNMENT & DECLARATION

WHEREAS, We Bong Jin Seo, Bon Kee Kim, Myung Jun Jin and Tae Hun Kim (hereinafter the "Assignors"), residing at (Dasan Tower, Sampyeong-dong) 3F, 49, Daewangpangyo-ro 644 beong-gil, Bundang-gu, Seongnam-si, Gyeonggi-do, 13493, Republic of Korea believe we are the original sole inventors of certain inventions or improvements claimed and/or disclosed in an application for Letters Patent which we have made, TOUCH INPUT DEVICE FOR DETECTING PRESSURE WITH DISPLAY NOISE COMPENSATION filed concurrently herewith; and

WHEREAS, the Application was made or authorized to be made by us.

WHEREAS, We hereby acknowledge that any willful false statement made in this Assignment & Declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, HiDeep Inc. (hereinafter the "Assignee"), of (Dasan Tower, Sampyeong-dong) , 3F, 49, Daewangpangyo-ro 644 beong-gil, Bundang-gu, Seongnam-si, Gyeonggi-do, 13493, Republic of Korea is desirous of acquiring the entire right, title and interest in and to the Application, all inventions or improvements disclosed and/or claimed in the Application, and in, to and under any and all Letters Patent which may be granted on or as a result thereof in any and all countries, including the right to file, prosecute and otherwise pursue the Application and any and all U.S. and foreign applications directed to the inventions or improvements disclosed and/or claimed therein, in the name of Assignee as Applicant.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, we, said Assignors, do hereby sell, assign, transfer and set over to Assignee, the entire right, title and interest in and to (1) the Application, (2) all inventions, improvements, and ideas disclosed and/or claimed in the Application, (3) any and all continuations, continuation-in-parts, divisionals, and/or non-provisionals of the Application and/or directed to the inventions, improvements, and ideas disclosed and/or claimed in the Application, (4) any and all patent applications claiming priority directly or indirectly to the Application, (5) and all renewals of and substitutes for the Application, and (6) to all Letters Patent which may be granted on or as a result of the foregoing in the United States and any and all other countries, and 6) any reissue or reissues or extension or extensions of said Letters Patent or the Application, and assign to and authorize said Assignee, to file prosecute and otherwise pursue, in the name of Assignee as applicant, all of the aforementioned applications for Letters Patent in all countries, the same to be held and enjoyed by Assignee, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Letters Patent, respectively, may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by Assignor had this Assignment not been made.

AND we hereby covenant that we have full right to convey the entire interest herein assigned and that we have not executed and will not execute any agreement in conflict herewith, and we further covenant and agree that we will each time request is made and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to the Application, said inventions or improvements disclosed or claimed in the Application, all applications claiming priority directly or indirectly thereto, and said Letters Patent to said

PATENT

Assignee, its successors, assigns, nominees, or legal representatives, and we agree to communicate to said Assignee or to its nominees all known facts respecting said inventions or improvements, the Application, all applications claiming priority directly or indirectly thereto, and said Letters Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisional, continuing, reissue and foreign applications, to make all rightful oaths, and generally to do everything possible to aid said Assignee, its successors, assigns, nominees and legal representatives to obtain and enforce for its or their own benefit proper patent protection for said inventions or improvements in any and all countries, all such actions to be at the sole expense of Assignee.

AND, we hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any country or countries foreign to the United States whose duty it is to issue patents on applications as aforesaid, to issue to said assignee, as assignee of the entire right, title and interest, any and all Letters Patent for the Application and all said inventions or improvements disclosed and/or claimed therein, and all applications claiming priority directly or indirectly thereto, including any and all Letters Patent of the United States which may be issued and granted on or as a result of the aforesaid, in accordance with the terms of this Assignment.

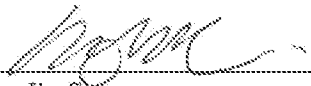
IN WITNESS WHEREOF, we have hereunto set my hand and seal.

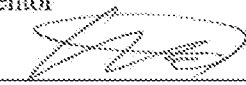
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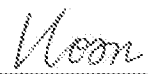
May, 14, 2019
Date

May 14. 2019
Date


Bong Jin Seo
Inventor


Bon Kee Kim
Inventor


Myung Jun Jin
Inventor


Tae Hun Kim
Inventor